

ABSTRACT

A method for manufacturing an optical semiconductor package includes a first step of temporarily bonding, to a substrate, a light receiving element and a first end portion of a metal pillar, a second step
5 of forming a molding resin covering the light receiving element and the metal pillar on the substrate, a third step of exposing a second surface of the light receiving element and a second end portion of the metal pillar by polishing or grinding the molding resin from a side facing the second surface of the light receiving element, a fourth step of forming a first
10 wiring layer on the second surface of the light receiving element and on an end surface of the molding resin, a fifth step of separating the substrate from the light receiving element, the metal pillar, and the molding resin, and a sixth step of forming a second wiring on a side opposite to a side on which the first wiring layer is positioned with respect to the light
15 receiving element and the molding resin after the fifth step.

Fig.1